

IEC 62769-103-1

Edition 3.0 2023-04 REDLINE VERSION

INTERNATIONAL STANDARD



Field Device Integration (FDI)® – Standards
Part 103-1: Profiles – PROFIBUS

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IEC 62769-103-1:2023

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ICS 25.040.40; 35.100.05 ISBN 978-2-8322-6857-5

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FIELD DEVICE INTEGRATION (FDI®) -

Part 103-1: Profiles - PROFIBUS

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IEC 62769-103-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2020. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added DEVICE_ID to the ProfibusIdentificationType and namespace to Annex A and Annex B:
- b) added mapping from PB standard parameters to PA DIM.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/862/CDV	65E/919/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 62769 series, published under the general title *Field device* integration (FDI^{\otimes}), can be found on the IEC website. 2023

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
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- · replaced by a revised edition, or
- amended.

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FIELD DEVICE INTEGRATION (FDI®) -

Part 103-1: Profiles - PROFIBUS

1 Scope

This part of IEC 62769 specifies an FDI $^{\otimes 1}$ profile of IEC 62769 for IEC 61784-1_CP 3/1 (PROFIBUS DP)² and IEC 61784-1_CP3/2 (PROFIBUS PA)⁴.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61784-1, Industrial communication networks - Profiles - Part 1: Fieldbus profiles

IEC 61804 (all parts), Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL)

IEC 62541-100:2015, OPC Unified Architecture - Part 100: Device Interface OPC UA for Devices

IEC 62769-2³, Field device integration (FDI[®]) – Part 2: FDI-Client

IEC 62769-4⁴, Field device integration (FDI[®]) – Part 4: FDI[®] Packages

IEC 62769-5⁵, Field device integration (FDI®) – Part 5: FDI-Information Model

IEC 62769-7⁶, Field Device Integration (FDI[®]) – Part 7: FDI-Communication Devices

PI Order No.: 2.122:2008, Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD; available at www.PROFIBUS.com

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³ Under preparation. Stage at the time of publication: IEC/RFDIS 62769-2:2020.

⁴ Under preparation. Stage at the time of publication: IEC/RFDIS 62769-4:2020.

⁵ Under preparation. Stage at the time of publication: IEC/RFDIS 62769-5:2020.

⁶—Under preparation. Stage at the time of publication: IEC/RFDIS 62769-7:2020.

3 Terms, definitions, abbreviated terms and conventions acronyms

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 61784-1, IEC 61804 (all parts), IEC 62541-100, IEC 62769-4, IEC 62769-5, IEC 62769-7 and PI Order No.: 2.122:2008 apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

3.2 Abbreviated terms and acronyms

For the purposes of this document, the following abbreviated terms and acronyms apply:

EDD	Electronic Device Description
EDDL	Electronic Device Description Language (see IEC 61804 (all parts))
GSD	General station description (see PI Order No.: 2.122:2008)
I&M	Identification and maintenance function
UUID	Universally unique identifier (see ISO/IEC 11578 IEC 62769-8)
XML	Extensible markup language (see REC-xml-20081126)

4 Conventions

4.1 EDDL syntax

This document specifies content for the EDD component that is part of FDI® Communication 2023 Packages. The specification content using EDDL syntax uses the font Courier New. The EDDL syntax is used for method signature, variable, data structure and component declarations.

4.2 XML syntax

XML syntax examples use font Courier New. The XML syntax is used to describe XML document schema.

Example: <xs:simpleType name="ExampleType">

4.3 Capitalizations

The IEC 62769 series uses capitalized terms to emphasize that these terms have a FDI[®] specific meaning.

Some of these terms using an acronym as a prefix for example

- FDI[®] Client, or
- FDI[®] Server.

Some of these terms are compound terms such as:

- Communication Servers, or
- Profile Package.

Parameter names or attributes are concatenated to a single term, where the original terms start in this term with a capital letter such as:

- ProtocolSupportFile or
- · ProtocolType.

Parameter names or attributes can also be constructed by using an underscore character to concatenate two or more terms such as:

- PROFILE ID or
- Profibus PA Network

5 Profile for PROFIBUS

5.1 General

This profile document to the FDI[®] specification in IEC 62769 specifies the protocol specifics needed for FDI[®] Packages describing Communication Servers, Gateways and Devices.

For Communication Servers this document defines also protocol specifics as these need to be considered in the Communication Servers hosted Information Model.

Annex B defines the XML schema for Direct Access Services. Annex C provides an overview of mapping PROFIBUS standard parameters to PA DIM.

5.2 Catalog profile ttps://standards.iteh.ai

5.2.1 Protocol support file

5.2.1.1 FDI® Device Package

Protocol specific attachments are mentioned in the Package Catalog as defined in IEC 62769-5. A communication feature list (GSD) file according to PI Order No.: 2.122:2008 is a mandatory attachment for FDI® Device Packages representing PROFIBUS DP and PROFIBUS PA devices. Table 1 specifies the parameters of the ProtocolSupportFile in the FDI® Device Package.

Table 1 - ProtocolSupportFile	for $FDI^{ exttt{ iny B}}$	Device	Packages
-------------------------------	----------------------------	--------	----------

Parameter	Description
Content Type	text/plain
Root Namespace	empty
Source Relationship	http://fdi-cooperation.com/2010/relationship/attachment-protocol
Filename	According to PI Order No.: 2.122:2008

5.2.1.2 FDI[®] Communication Packages

A GSD file as specified in PI Order No.: 2.122:2008 is an optional attachment for FDI[®] Communication Packages representing PROFIBUS DP and PROFIBUS PA devices. Table 2 specifies the parameters of ProtocolSupportFile for FDI[®] Communication Packages.

Table 2 – ProtocolSupportFile for FDI® Communication Packages

Parameter	Description
Content Type:	text/plain
Root Namespace:	empty
Source Relationship:	http://fdi-cooperation.com/2010/relationship/attachment-protocol
Filename:	According to PI Order No.: 2.122:2008

CommunicationProfile definition 5.2.2

IEC 62769-4 defines a CommunicationProfileT string for the Catalog XML schema. Table 3 defines the PROFIBUS specific values for this string.

Table 3 - PROFIBUS CommunicationProfile definition schema

Profile Identifier	Protocol
"profibus_dp"	PROFIBUS DP/V0; PROFIBUS DP/V1; PROFIBUS DP/V2
"profibus_pa"	PROFIBUS PA

5.2.3 Profile device

A Profile Package shall provide the catalog values for profile devices, enabling the FDI® Server to leverage a generic device description, if a specific one is not available. The definitions in Table 4 focus on catalog content that is vendor independent.

Table 4 - Catalog values for profile devices

Element	Attribute	IFC 62769-103-1-2023 Content
PackageType	og/st a ndar	Profile 0:529e-aaa9-4563-8526-61e285d4c0e0/jec-62769-103-1
Manufacturer	_	Empty
DeviceModel	_	The allowed profile identifier values (PROFILE_ID) are provided by PROFIBUS & PROFINET International (PI). PI provides and maintains an XML file (Profile_ID_Table) containing the assignment of PROFILE_ID to profiles.
		It is available at http://www.profibus.com/IM/Profile_ID_Table.xml
		The file can be downloaded by any engineering or service tool whenever it is connected to the Internet.
		NOTE—More information is provided in PI Order No.: 3.502 (I&M Profile) and related profile definitions are referred therein.
		The string format shall be hexadecimal starting with 0x, e.g. '0x3D00'.

5.2.4 **Protocol version information**

IEC 62769-4 defines an element type named InterfaceT for the Catalog XML schema. The element type InterfaceT contains an element named Version which is supposed to provide version information about the applied communication protocol profile. The value has to follow the IEC 62769-4 defined version information schema defined in the element type VersionT. Table 5 describes how to apply the currently known protocol versions defined by the non-profit consortium PROFIBUS & PROFINET International. The general rule is to apply the value "0" for parts of the version information according to IEC 62769-4 that are not used in currently known protocol versions.

Table :	5 –	Version	mapping	examples ⁷
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Protocol / Version	InterfaceT Version value
PROFIBUS DP/V0	0.0.0ª
PROFIBUS DP/V1	1.0.0ª
PROFIBUS DP/V2	2.0.0ª
PROFIBUS PA 3.02	3.2.0 ^b
PROFIBUS PA 4.0	4.0.0 ^b

- The protocols PROFIBUS DP/V0, PROFIBUS DP/V1 and PROFIBUS DP/V2 contain a single number. This number is considered to be the major version. The minor and built numbers are set to "0".
- The currently known PROFIBUS PA profile numbers are considered to provide major and minor version information. Leading zeros are not considered in version value evaluation since only the actual decimal values are relevant.

5.3 Associating a Package with a device

5.3.1 Device type identification mapping

The purpose of device type identification mapping is to enable FDI® host systems to compare the scan result against the topology representation in the Information Model. FDI® host systems shall also be enabled to determine the FDI® Device Package that fits for a device entry contained in the scan result. This will enable the user of an FDI® host system to synchronize the Information Model with the actual installation.

The Communication Server implemented scan service (defined in 5.5.1.7) provides the scan result through an XML document (the schema is defined in Clause A.6).

The Gateway implemented scan service (defined in 5.5.2.7) provides the scan result by means of the Information Model that contains data structures created from EDD content as specified in 5.5.2.7.

Common for both ways of presenting the scan result is that scan results contain device type identification and device instance identification.

FDI® host systems comparing the actual network topology configuration against the topology representation in the Information Model shall be enabled to handle the following situations:

- a) The physical Device instance identified at a specific device address is not logically present in the Information Model (as Instance): Enable the FDI® Host system to find the appropriate FDI® Device package according to the device catalog information.
- b) The physical Device instance identified by the device address is logically present in the Information Model (as Instance): Enable the FDI® Host system to compare device type information presented in scan result (see the identification in Clause A.6) and the device type specific information of the Instance present in the Information Model.

The FDI® Device package contains device type identification information that can be compared to scan result based on the Catalog Schema in IEC 62769-4 defining the XML (simple) element types "DeviceModel" and "Manufacturer". Both types are used in the (complex) element types "Protocol" and "RegDeviceType".

⁷ The given table can be considered to be an example only since this document cannot foresee how future protocol versions will be defined.

As a result of the FDI[®] Package deployment the FDI[®] Package information is then present in the Information Model as the specified Functional Group Identification containing Ident Number and Manufacturer ID (see 5.4.3). The Ident Number matches with the GSD specified Ident Number. Manufacturer ID is specified through the I&M profile defined VendorID and DeviceID (see 5.4.3).

If a device is used as a profile device, the Ident Number returned in the scan result does not fit to the Ident Number within the GSD. In this case, DEVICE ID can be used to identify the FDI® Package.

The mapping between different device identification data sources is described in Table 6. Since scan results provided by the Communication Server or Gateway can convey data that is produced by the device (firmware) the device type identification mapping shall be supported by providing corresponding data in the FDI® Device Package contained Catalog and Information Model.

FDI [®] Device Package	Information Model	Communication Server provided scan result	Gateway provided scan result
Catalog specified type Manufacturer	FunctionalGroup: Identification Browse Name: Manufacturer_ID	Element (path): ConnectionPoint/Identification Attribute: Manufacturer_ID	COLLECTION ConnectionPoint. Identification. Manufacturer_ID
Catalog specified type DeviceModel	FunctionalGroup: Identification Browse Name: Ident_Number	Element (path): ConnectionPoint/Identification Attribute: Ident_Number	COLLECTION ConnectionPoint. Identification. Ident_Number

Table 6 - Device identification information mapping

5.3.2 Device type revision mapping

IEC 62769-4 envisions a concept that allows to determine the compatibility between an FDI® Device Package and a Device. IEC 62769-4 specifies a life cycle management process bearing on a single version information provided for the entire device.

NOTE—PROFIBUS related specifications, for example PI Order No.: 2.122:2008 (GSD) and PI Order No.: 3.502:2009 (I&M) splits the device type revision into software and hardware related information. The GSD specifies the attributes Hardware Release and Software Release. The I&M specifies HARDWARE REVISION and SOFTWARE REVISION. Hardware Release and HARDWARE REVISION-shall match alwavs. Software Release SOFTWARE REVISION will shall match always.

The goal of 5.3.2 is to describe the translation rules between PROFIBUS related specifications, describing their way of providing the version information, and the IEC 62769-4 specified way of containing the version information that can be compared against the version read from the device. The purpose is to determine the compatibility between an FDI® Device Package and a Device. Figure 1 depicts the problem.

Figure 1 - Version mapping problem

The firmware of a device implements the data exchange interface which shall be described by means of the FDI® Device Package content (EDD). A device firmware that implements the PROFIBUS PA profile enables the reading of the values SOFTWARE_REVISION and HARDWARE_REVISION. The access to these values shall be described in the EDD contained in the FDI® Device Package.

Firmware modifications that affect the firmware implemented data exchange interface shall be reflected in the FDI[®] Device Package. Such firmware and device description modification shall be visible in the SOFTWARE_REVISION and Software_Release.

Hardware related modifications shall be captured in the HARDWARE_REVISION and Hardware_Release. Hardware related modifications do not necessarily always require a firmware update. Thus HARDWARE_REVISION and Hardware_Release cannot be used to determine compatibility between a device and the FDI® Device Package. But if a hardware modification requires firmware modifications both HARDWARE_REVISION and SOFTWARE_REVISION shall be changed. Hardware_Release and Software_Release shall be changed accordingly.

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The IEC 62769-4 specifies the Catalog schema and an element DeviceVersion which is used in the element type declaration ListOfSupportedDeviceVersions. The value of the DeviceVersion shall be compared to the device provided SOFTWARE_REVISION or the GSD provided Software_Release in order to determine the compatibility between an FDI® Device Package and a device.

The data format for the SOFTWARE_REVISION is a string while the DeviceVersion expects three numbers for major, minor, and revision. Therefore the following rules apply: If the string has the format <integer>.<integer> this is transferred to major, minor, and revision (in the same order). <integer> references to simple integer number in the string such as '1' or '12', not to other representations such as hexadecimal format (e.g. 0x001A). If <integer>.<integer> is provided, this is transferred to major and minor and '0' is used for revision. If only an <integer> is provided, this is transferred to major and '0' is used for minor and revision. A leading character or a leading character and whitespace shall be ignored. For a string in any other format the revision number shall not be considered to select the correct FDI® package.

5.4 Information Model mapping

5.4.1 ProtocolType definition

The concept to derive PROFIBUS DP and PROFIBUS PA specific Network Types applies to the protocol type definition.